



NOTE

All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters [and inches]. Unless otherwise specified, dimensions have a tolerance of ± 0.13 [$\pm .005$] and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of the EEPROM Assembly Module. This assembly contains a plug, a TPA, two contacts, and a microchip EEPROM Chip. The plug and contacts are modified versions of the EP 2.5 connector series, designed to mate to the EP 2.5 header assembly.

Basic terms and features of this product are listed in Figure 1.

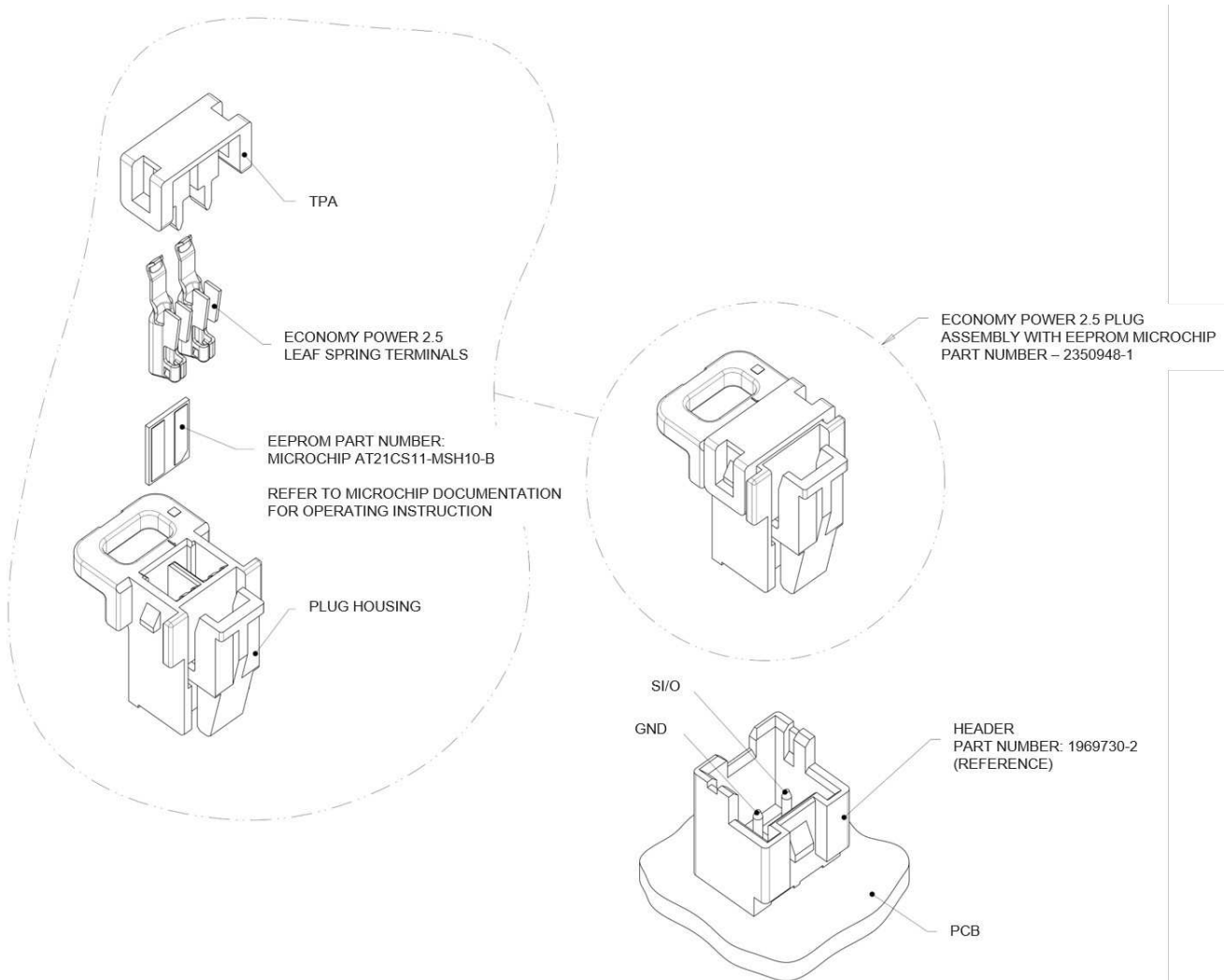


Figure 1

2. REFERENCE MATERIAL

2.1. Revision Summary

- Added Paragraph 3.2.A
- Updated Section 4 and Figure 2
- EEPROM Part Number added to Figure 1

2.2. Customer Assistance

Reference Product Base Part Number 2350948 and Product Code Y012 are representative of the EEPROM Assembly Module. Use of these numbers will identify the product line and help you to obtain product and tooling information when visiting www.te.com or calling the number at the bottom of page 1.

2.3. Drawings

Customer drawings for product part numbers are available from www.te.com. Information contained in the customer drawing takes priority.

2.4. Manuals

Manual [402-40](#) can be used as a guide to soldering. This manual provides information on various flux types and characteristics with the commercial designation, flux removal procedures, and a checklist for information on soldering problems.

2.5. Specifications

Product Specification [108-143144](#) provides product performance and test results for the EEPROM Assembly Module. Product Specification [108-2418](#) provides product performance and test results for the EP 2.5 header assembly.

2.6. Instructional Material

Instructional material that pertain to this product are:

[114-13315](#) Application Specification – EP 2.5 Connector System

Refer to documentations from Microchip for instruction on how to read / write to the memory.

3. REQUIREMENTS

3.1. Safety

Do not stack product shipping containers so high that the containers buckle or deform.

3.2. Storage

A. Storage Requirements

Products are shipped and must be stored in an antistatic bag to prevent damage caused by electrostatic discharge (ESD). The microchip is IEC 61000-4-2 Level 4 ESD Compliant (± 8 kV Contact, ± 15 kV Air Discharge).

B. Ultraviolet Light

Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the product material.

C. Shelf Life

Prior to shipment, products are subject to a 100% continuity check. The product should remain in the shipping containers until ready for use to prevent deformation to components. The product should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance. The EEPROM Assembly Module has a shelf life of 3 years.

D. Chemical Exposure

[Type text]

Do not store product near any chemical listed below as they may cause stress corrosion cracking in the material.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates



NOTE

Where the above environmental conditions exist, phosphor-bronze contacts are recommended instead of brass if available.

3.3. Assembly

1. Solder the EP 2.5 header assembly to the PC board per requirements specified in [114-13315](#).
2. Mate the EEPROM Assembly Module to the EP 2.5 header assembly, ensuring that the connector latch on the EEPROM Assembly Module is fully engaged with the header assembly locking ramp.

3.4. Replacement and Repair



CAUTION

Defective or damaged product must not be used. The assembly modules and headers are not repairable.

3.5. Tie Wrap

A tie wrap may be installed in the lanyard area of the EEPROM Assembly Module. The lanyard area is designed to accept the Nylon 6.6 PLT1M tie wrap. When assembled, the tie wrap must have slack and may not provide a tensile force when mated to the header.

4. QUALIFICATION

The EEPROM Assembly Module is subject to the qualification requirements listed in [108-143144](#).

5. VISUAL AID

The illustration below shows a typical application of this product. This illustration should be used by production personnel to ensure a correctly applied product. Applications which do not appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

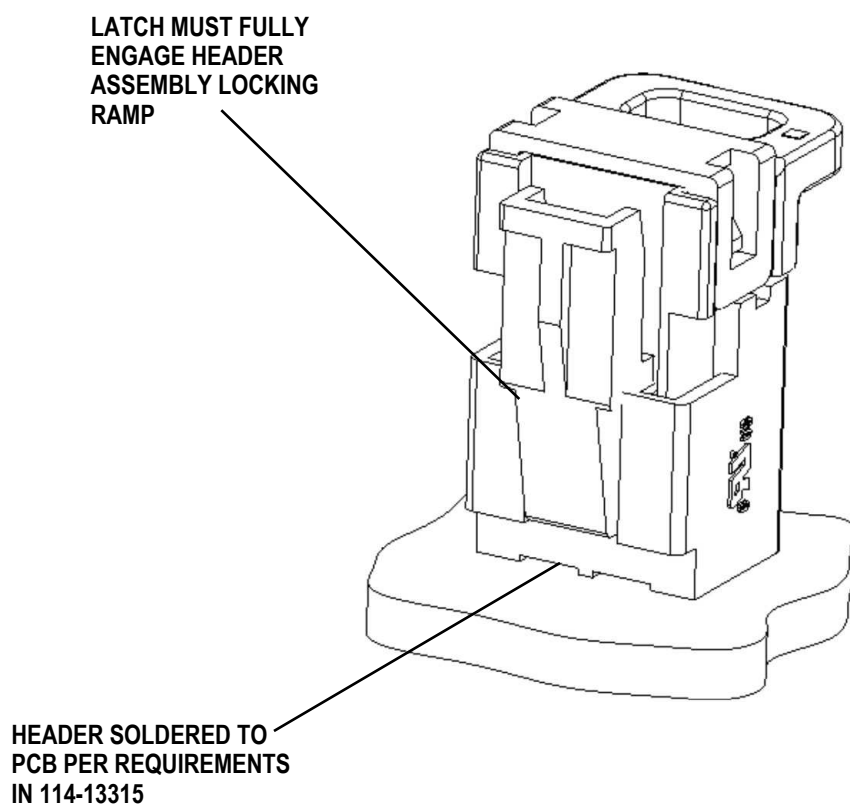


Figure 2: Visual Aid